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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, LVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8f041ahh020sg

List of Figures

Table 2. Signal Descriptions (Continued)

Signal Mnemonic	I/O	Description
Reset		
$\overline{\text{RESET}}$	I/O	RESET. Generates a Reset when asserted (driven Low). Also serves as a reset indicator; the Z8 Encore! XP forces this pin low when in reset. This pin is open-drain and features an enabled internal pull-up resistor.
Power Supply		
V_{DD}	I	Digital Power Supply.
AV_{DD}	I	Analog Power Supply.
V_{SS}	I	Digital Ground.
AV_{SS}	I	Analog Ground.

Notes:
1. PB6 and PB7 are only available in 28-pin packages without ADC. In 28-pin packages with ADC, they are replaced by AV_{DD} and AV_{SS}.
2. The AV_{DD} and AV_{SS} signals are available only in 28-pin packages with ADC. They are replaced by PB6 and PB7 on 28-pin packages without ADC.

Pin Characteristics

Table 3 describes the characteristics for each pin available on the Z8 Encore! XP F082A Series 20- and 28-pin devices. Data in Table 3 is sorted alphabetically by the pin symbol mnemonic.

Table 4 on page 14 provides detailed information about the characteristics for each pin available on the Z8 Encore! XP F082A Series 8-pin devices.

Note: All six I/O pins on the 8-pin packages are 5 V-tolerant (unless the pull-up devices are enabled). The column in Table 3 below describes 5 V-tolerance for the 20- and 28-pin packages only.

Register Map

Table 7 provides the address map for the Register File of the Z8 Encore! XP F082A Series devices. Not all devices and package styles in the Z8 Encore! XP F082A Series support the ADC, or all of the GPIO Ports. Consider registers for unimplemented peripherals as Reserved.

Table 7. Register File Address Map

Address (Hex)	Register Description	Mnemonic	Reset (Hex)	Page
General-Purpose RAM				
Z8F082A/Z8F081A Devices				
000–3FF	General-Purpose Register File RAM	—	XX	
400–EFF	Reserved	—	XX	
Z8F042A/Z8F041A Devices				
000–3FF	General-Purpose Register File RAM	—	XX	
400–EFF	Reserved	—	XX	
Z8F022A/Z8F021A Devices				
000–1FF	General-Purpose Register File RAM	—	XX	
200–EFF	Reserved	—	XX	
Z8F012A/Z8F011A Devices				
000–0FF	General-Purpose Register File RAM	—	XX	
100–EFF	Reserved	—	XX	
Timer 0				
F00	Timer 0 High Byte	T0H	00	90
F01	Timer 0 Low Byte	T0L	01	90
F02	Timer 0 Reload High Byte	T0RH	FF	91
F03	Timer 0 Reload Low Byte	T0RL	FF	91
F04	Timer 0 PWM High Byte	T0PWMH	00	92
F05	Timer 0 PWM Low Byte	T0PWML	00	92
F06	Timer 0 Control 0	T0CTL0	00	85
F07	Timer 0 Control 1	T0CTL1	00	86

Notes:
1. XX = Undefined.
2. Refer to the eZ8 CPU Core User Manual (UM0128).

Bit	Description (Continued)
[6] TPOL	**Timer Input/Output Polarity** Operation of this bit is a function of the current operating mode of the timer. **ONE-SHOT Mode** When the timer is disabled, the Timer Output signal is set to the value of this bit. When the timer is enabled, the Timer Output signal is complemented upon timer Reload. **CONTINUOUS Mode** When the timer is disabled, the Timer Output signal is set to the value of this bit. When the timer is enabled, the Timer Output signal is complemented upon timer Reload. **COUNTER Mode** If the timer is enabled the Timer Output signal is complemented after timer reload. 0 = Count occurs on the rising edge of the Timer Input signal. 1 = Count occurs on the falling edge of the Timer Input signal. **PWM SINGLE OUTPUT Mode** 0 = Timer Output is forced Low (0) when the timer is disabled. When enabled, the Timer Output is forced High (1) upon PWM count match and forced Low (0) upon reload. 1 = Timer Output is forced High (1) when the timer is disabled. When enabled, the Timer Output is forced Low (0) upon PWM count match and forced High (1) upon reload. **CAPTURE Mode** 0 = Count is captured on the rising edge of the Timer Input signal. 1 = Count is captured on the falling edge of the Timer Input signal. **COMPARE Mode** When the timer is disabled, the Timer Output signal is set to the value of this bit. When the timer is enabled, the Timer Output signal is complemented upon timer Reload.

UART Interrupts

The UART features separate interrupts for the transmitter and the receiver. In addition, when the UART primary functionality is disabled, the Baud Rate Generator can also function as a basic timer with interrupt capability.

Transmitter Interrupts

The transmitter generates a single interrupt when the Transmit Data Register Empty bit (TDRE) is set to 1. This indicates that the transmitter is ready to accept new data for transmission. The TDRE interrupt occurs after the Transmit Shift Register has shifted the first bit of data out. The Transmit Data Register can now be written with the next character to send. This action provides 7 bit periods of latency to load the Transmit Data Register before the Transmit Shift Register completes shifting the current character. Writing to the UART Transmit Data Register clears the TDRE bit to 0.

Receiver Interrupts

The receiver generates an interrupt when any of the following actions occur:

- A data byte is received and is available in the UART Receive Data Register. This interrupt can be disabled independently of the other receiver interrupt sources. The received data interrupt occurs after the receive character has been received and placed in the Receive Data Register. To avoid an overrun error, software must respond to this received data available condition before the next character is completely received.

Note: In MULTIPROCESSOR Mode (MPEN=1), the receive data interrupts are dependent on the multiprocessor configuration and the most recent address byte.

- A break is received.
- An overrun is detected.
- A data framing error is detected.

UART Overrun Errors

When an overrun error condition occurs the UART prevents overwriting of the valid data currently in the Receive Data Register. The Break Detect and Overrun status bits are not displayed until after the valid data has been read.

After the valid data has been read, the UART Status 0 Register is updated to indicate the overrun condition (and Break Detect, if applicable). The RDA bit is set to 1 to indicate that the Receive Data Register contains a data byte. However, because the overrun error occurred, this byte may not contain valid data and must be ignored. The BRKD bit indicates if the overrun was caused by a break condition on the line. After reading the status

The baud rate is set by the UART's Baud Rate Generator and supports IrDA standard baud rates from 9600 baud to 115.2 kbaud. Higher baud rates are possible, but do not meet IrDA specifications. The UART must be enabled to use the infrared endec. The infrared endec data rate is calculated using the following equation:

$$\text{Infrared Data Rate (bits/s)} = \frac{\text{System Clock Frequency (Hz)}}{16 \times \text{UART Baud Rate Divisor Value}}$$

Transmitting IrDA Data

The data to be transmitted using the infrared transceiver is first sent to the UART. The UART's transmit signal (TXD) and baud rate clock are used by the IrDA to generate the modulation signal (IR_TXD) that drives the infrared transceiver. Each UART/Infrared data bit is 16 clocks wide. If the data to be transmitted is 1, the IR_TXD signal remains low for the full 16 clock period. If the data to be transmitted is 0, the transmitter first outputs a 7 clock low period, followed by a 3 clock high pulse. Finally, a 6 clock low pulse is output to complete the full 16 clock data period. Figure 17 displays IrDA data transmission. When the infrared endec is enabled, the UART's TXD signal is internal to the Z8 Encore! XP F082A Series products while the IR_TXD signal is output through the TXD pin.

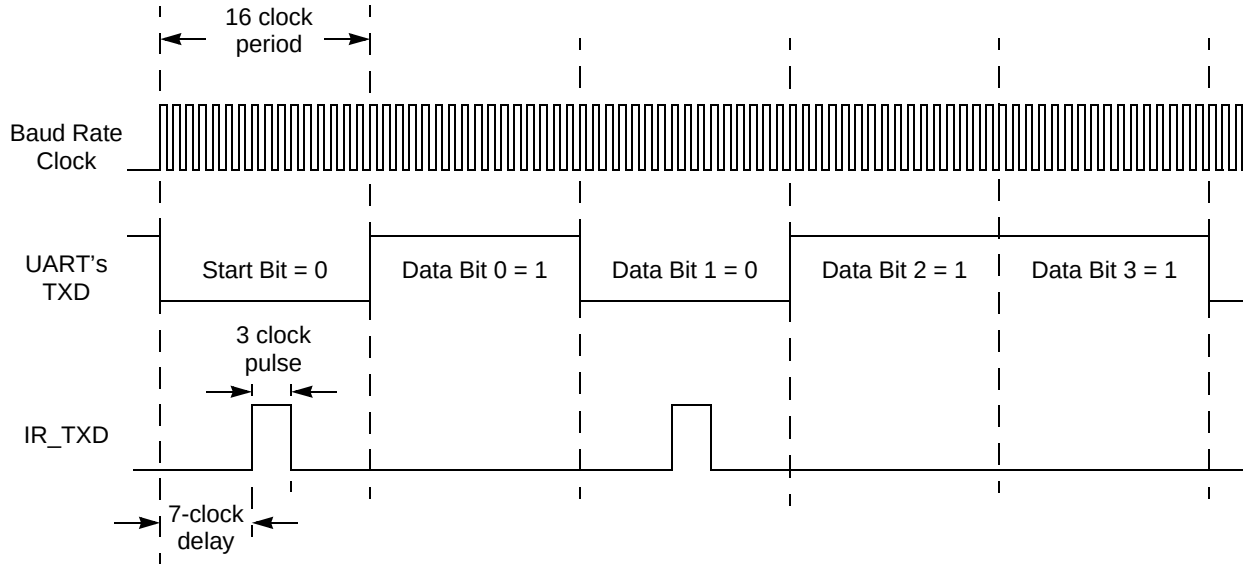

Figure 17. Infrared Data Transmission

#3	#3	#3	#3

4. Round the result and discard the least significant two bytes (equivalent to dividing by 2^{16}).

#3	#3	#3	#3

–

0x00	0x00	0x80	0x00

=

#4 MSB	#4 LSB

5. Determine the sign of the gain correction factor using the sign bits from Step 2. If the offset-corrected ADC value *and* the gain correction word both have the same sign, then the factor is positive and remains unchanged. If they have differing signs, then the factor is negative and must be multiplied by –1.

#5 MSB	#5 LSB

6. Add the gain correction factor to the original offset corrected value.

#5 MSB	#5 LSB

+

#1 MSB	#1 LSB

=

#6 MSB	#6 LSB

7. Shift the result to the right, using the sign bit determined in Step 1, to allow for the detection of computational overflow.

S →	#6 MSB	#6 LSB

Table 74. ADC Control/Status Register 1 (ADCCTL1)

Bit	7	6	5	4	3	2	1	0
Field	REFSELH	Reserved				BUFMODE[2:0]		
RESET	1	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Address	F71H							

Bit	Description
[7] REFSELH	**Voltage Reference Level Select High Bit** In conjunction with the Low bit (REFSELL) in ADC Control Register 0, this determines the level of the internal voltage reference; the following details the effects of {REFSELH, REFSELL}; this reference is independent of the Comparator reference. 00= Internal Reference Disabled, reference comes from external pin. 01= Internal Reference set to 1.0V. 10= Internal Reference set to 2.0V (default). 11= Reserved.
[6:3]	**Reserved** These bits are reserved and must be programmed to 0000.
[2:0] BUFMODE[2:0]	**Input Buffer Mode Select** 000 = Single-ended, unbuffered input. 001 = Single-ended, buffered input with unity gain. 010 = Reserved. 011 = Reserved. 100 = Differential, unbuffered input. 101 = Differential, buffered input with unity gain. 110 = Reserved. 111 = Reserved.

ADC Data High Byte Register

The ADC Data High Byte (ADCD_H) Register contains the upper eight bits of the ADC output. The output is an 13-bit two’s complement value. During a single-shot conversion, this value is invalid. Access to the ADC Data High Byte Register is read-only. Reading the ADC Data High Byte Register latches data in the ADC Low Bits Register.

Table 75. ADC Data High Byte Register (ADCD_H)

Bit	7	6	5	4	3	2	1	0
Field	ADCDH							
RESET	X	X	X	X	X	X	X	X
R/W	R	R	R	R	R	R	R	R
Address	F72H							
X = Undefined.								

Bit	Description
[7:0] ADCDH	**ADC Data High Byte** This byte contains the upper eight bits of the ADC output. These bits are not valid during a single-shot conversion. During a continuous conversion, the most recent conversion output is held in this register. These bits are undefined after a Reset.

ADC Data Low Byte Register

The ADC Data Low Byte (ADCD_L) Register contains the lower bits of the ADC output plus an overflow status bit. The output is a 13-bit two's complement value. During a single-shot conversion, this value is invalid. Access to the ADC Data Low Byte Register is read-only. Reading the ADC Data High Byte Register latches data in the ADC Low Bits Register.

Table 76. ADC Data Low Byte Register (ADCD_L)

Bit	7	6	5	4	3	2	1	0
Field	ADCDL					Reserved		OVF
RESET	X	X	X	X	X	X	X	X
R/W	R	R	R	R	R	R	R	R
Address	F73H							
X = Undefined.								

Bit	Description
[7:3] ADCDL	**ADC Data Low Bits** These bits are the least significant five bits of the 13-bits of the ADC output. These bits are undefined after a Reset.

Debugger. Writing an invalid value or an invalid sequence returns the Flash Controller to its locked state. The Write-only Flash Control Register shares its Register File address with the read-only Flash Status Register.

Byte Read

To read a byte from the NVDS array, user code must first push the address onto the stack. User code issues a `CALL` instruction to the address of the byte-read routine (`0x1000`). At the return from the sub-routine, the read byte resides in working register R0 and the read status byte resides in working register R1. The contents of the status byte are undefined for read operations to illegal addresses. Also, the user code must pop the address byte off the stack.

The read routine uses 9 bytes of stack space in addition to the one byte of address pushed by the user. Sufficient memory must be available for this stack usage.

Because of the Flash memory architecture, NVDS reads exhibit a nonuniform execution time. A read operation takes between 44 µs and 489 µs (assuming a 20 MHz system clock). Slower system clock speeds result in proportionally higher execution times.

NVDS byte reads from invalid addresses (those exceeding the NVDS array size) return 0xff. Illegal read operations have a 2 µs execution time.

The status byte returned by the NVDS read routine is zero for successful read, as determined by a CRC check. If the status byte is nonzero, there was a corrupted value in the NVDS array at the location being read. In this case, the value returned in R0 is the byte most recently written to the array that does not have a CRC error.

Power Failure Protection

The NVDS routines employ error checking mechanisms to ensure a power failure endangers only the most recently written byte. Bytes previously written to the array are not perturbed.

A system reset (such as a pin reset or Watchdog Timer reset) that occurs during a write operation also perturbs the byte currently being written. All other bytes in the array are unperturbed.

Optimizing NVDS Memory Usage for Execution Speed

NVDS read time can vary drastically. This discrepancy is a trade-off for minimizing the frequency of writes that require post-write page erases, as indicated in Table 107. The NVDS read time of address N is a function of the number of writes to addresses other than N since the most recent write to address N, plus the number of writes since the most recent page erase. Neglecting effects caused by page erases and results caused by the initial condition in which the NVDS is blank, a rule of thumb is that every write since the most recent page erase causes read times of unwritten addresses to increase by 1 µs up to a maximum of (511-NVDS_SIZE) µs.

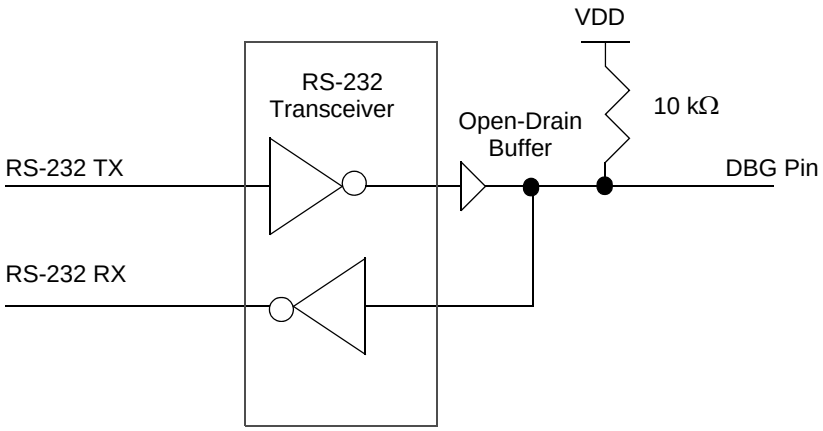

Figure 25. Interfacing the On-Chip Debugger's DBG Pin with an RS-232 Interface; #2 of 2

DEBUG Mode

The operating characteristics of the devices in DEBUG Mode are:

- The eZ8 CPU fetch unit stops, idling the eZ8 CPU, unless directed by the OCD to execute specific instructions
- The system clock operates unless in STOP Mode
- All enabled on-chip peripherals operate unless in STOP Mode
- Automatically exits HALT Mode
- Constantly refreshes the Watchdog Timer, if enabled

Entering DEBUG Mode

The operating characteristics of the devices entering DEBUG Mode are:

- The device enters DEBUG Mode after the eZ8 CPU executes a BRK (Breakpoint) instruction
- If the DBG pin is held Low during the final clock cycle of system reset, the part enters DEBUG Mode immediately (20-/28-pin products only)

Note: Holding the DBG pin Low for an additional 5000 (minimum) clock cycles after reset (making sure to account for any specified frequency error if using an internal oscillator) prevents a false interpretation of an Autobaud sequence (see the OCD Auto-Baud Detector/Generator section on page 183).

When selecting a new clock source, the system clock oscillator failure detection circuitry and the Watchdog Timer oscillator failure circuitry must be disabled. If SOFEN and WOFEN are not disabled prior to a clock switch-over, it is possible to generate an interrupt for a failure of either oscillator. The Failure detection circuitry can be enabled anytime after a successful write of OSCSEL in the OSCCTL Register.

The internal precision oscillator is enabled by default. If the user code changes to a different oscillator, it may be appropriate to disable the IPO for power savings. Disabling the IPO does not occur automatically.

Clock Failure Detection and Recovery

Should an oscillator or timer fail, there are methods of recovery, as this section describes.

System Clock Oscillator Failure

The Z8F04xA family devices can generate nonmaskable interrupt-like events when the primary oscillator fails. To maintain system function in this situation, the clock failure recovery circuitry automatically forces the Watchdog Timer oscillator to drive the system clock. The Watchdog Timer oscillator must be enabled to allow the recovery. Although this oscillator runs at a much slower speed than the original system clock, the CPU continues to operate, allowing execution of a clock failure vector and software routines that either remedy the oscillator failure or issue a failure alert. This automatic switch-over is not available if the Watchdog Timer is selected as the system clock oscillator. It is also unavailable if the Watchdog Timer oscillator is disabled, though it is not necessary to enable the Watchdog Timer reset function (see the Watchdog Timer chapter on page 93).

The primary oscillator failure detection circuitry asserts if the system clock frequency drops below 1kHz ±50%. If an external signal is selected as the system oscillator, it is possible that a very slow but nonfailing clock can generate a failure condition. Under these conditions, do not enable the clock failure circuitry (SOFEN must be deasserted in the OSCCTL Register).

Watchdog Timer Failure

In the event of a Watchdog Timer oscillator failure, a similar nonmaskable interrupt-like event is issued. This event does not trigger an attendant clock switch-over, but alerts the CPU of the failure. After a Watchdog Timer failure, it is no longer possible to detect a primary oscillator failure. The failure detection circuitry does not function if the Watchdog Timer is used as the system clock oscillator or if the Watchdog Timer oscillator has been disabled. For either of these cases, it is necessary to disable the detection circuitry by deasserting the WDFEN bit of the OSCCTL Register.

The Watchdog Timer oscillator failure detection circuit counts system clocks while looking for a Watchdog Timer clock. The logic counts 8004 system clock cycles before determining that a failure has occurred. The system clock rate determines the speed at which

Note: The stabilization time varies depending on the crystal, resonator or feedback network used. See Table 115 for transconductance values to compute oscillator stabilization times.

Figure 27 displays a recommended configuration for connection with an external fundamental-mode, parallel-resonant crystal operating at 20 MHz. Recommended 20 MHz crystal specifications are provided in Table 114. Printed circuit board layouts must add no more than 4 pF of stray capacitance to either the X_{IN} or X_{OUT} pins. If oscillation does not occur, reduce the values of capacitors C1 and C2 to decrease loading.

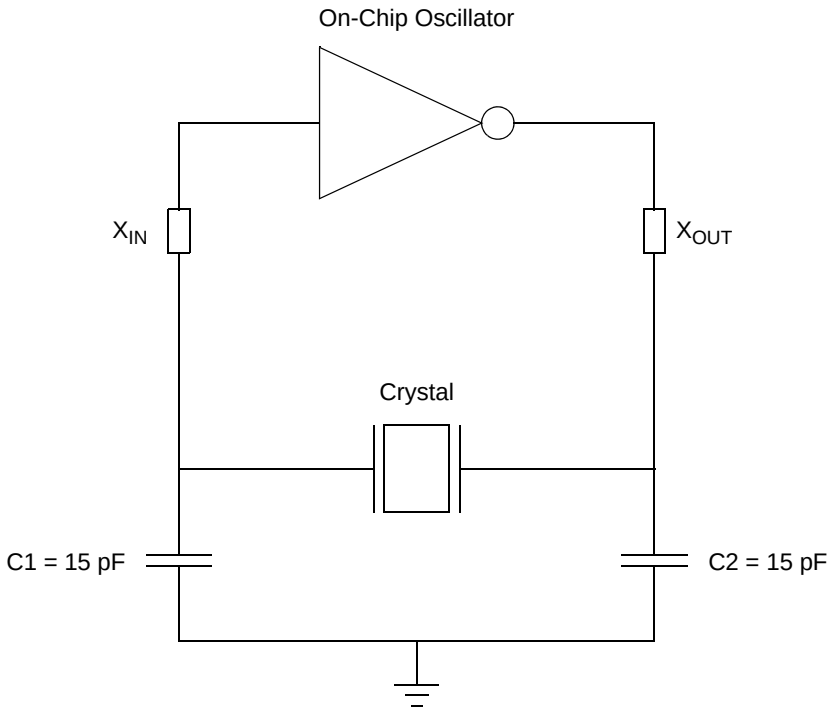

Figure 27. Recommended 20 MHz Crystal Oscillator Configuration

Table 123. CPU Control Instructions (Continued)

Mnemonic	Operands	Instruction
RCF	—	Reset Carry Flag
SCF	—	Set Carry Flag
SRP	src	Set Register Pointer
STOP	—	STOP Mode
WDT	—	Watchdog Timer Refresh

Table 124. Load Instructions

Mnemonic	Operands	Instruction
CLR	dst	Clear
LD	dst, src	Load
LDC	dst, src	Load Constant to/from Program Memory
LDCI	dst, src	Load Constant to/from Program Memory and Auto-Increment Addresses
LDE	dst, src	Load External Data to/from Data Memory
LDEI	dst, src	Load External Data to/from Data Memory and Auto-Increment Addresses
LDWX	dst, src	Load Word using Extended Addressing
LDX	dst, src	Load using Extended Addressing
LEA	dst, X(src)	Load Effective Address
POP	dst	Pop
POPX	dst	Pop using Extended Addressing
PUSH	src	Push
PUSHX	src	Push using Extended Addressing

Table 125. Logical Instructions

Mnemonic	Operands	Instruction
AND	dst, src	Logical AND
ANDX	dst, src	Logical AND using Extended Addressing
COM	dst	Complement
OR	dst, src	Logical OR
ORX	dst, src	Logical OR using Extended Addressing
XOR	dst, src	Logical Exclusive OR
XORX	dst, src	Logical Exclusive OR using Extended Addressing

Table 131. DC Characteristics (Continued)

		T_A = –40°C to +105°C (unless otherwise specified)				
Symbol	**Parameter**	**Minimum**	**Typical**	**Maximum**	**Units**	**Conditions**
V_{OH1}	High Level Output Voltage	2.4	–	–	V	I_{OH} = -2 mA; V_{DD} = 3.0 V High Output Drive disabled.
V_{OL2}	Low Level Output Voltage	–	–	0.6	V	I_{OL} = 20 mA; V_{DD} = 3.3V High Output Drive enabled.
V_{OH2}	High Level Output Voltage	2.4	–	–	V	I_{OH} = -20 mA; V_{DD} = 3.3V High Output Drive enabled.
I_{IH}	Input Leakage Current	–	±0.002	±5	µA	V_{IN} = V_{DD} V_{DD} = 3.3V;
I_{IL}	Input Leakage Current	–	±0.007	±5	µA	V_{IN} = V_{SS} V_{DD} = 3.3V;
I_{TL}	Tristate Leakage Current	–	–	±5	µA	
I_{LED}	Controlled Current Drive	1.8	3	4.5	mA	{AFS2,AFS1} = {0,0}
		2.8	7	10.5	mA	{AFS2,AFS1} = {0,1}
		7.8	13	19.5	mA	{AFS2,AFS1} = {1,0}
		12	20	30	mA	{AFS2,AFS1} = {1,1}
C_{PAD}	GPIO Port Pad Capacitance	–	8.0[2]	–	pF	
C_{XIN}	XIN Pad Capacitance	–	8.0[2]	–	pF	
C_{XOUT}	X_{OUT} Pad Capacitance	–	9.5[2]	–	pF	
I_{PU}	Weak Pull-up Current	30	100	350	µA	V_{DD} = 3.0 V–3.6 V
V_{RAM}	RAM Data Retention Voltage	TBD			V	Voltage at which RAM retains static values; no reading or writing is allowed.

Notes:
1. This condition excludes all pins that have on-chip pull-ups, when driven Low.
2. These values are provided for design guidance only and are not tested in production.

Table 139. Analog-to-Digital Converter Electrical Characteristics and Timing (Continued)

		V_{DD} = 3.0 V to 3.6 V T_A = 0°C to +70°C (unless otherwise stated)				
Symbol	**Parameter**	**Minimum**	**Typical**	**Maximum**	**Units**	**Conditions**
	Continuous Conversion Time	–	256	–	System clock cycles	All measurements but temperature sensor
			512			Temperature sensor measurement
	Signal Input Bandwidth	–	10		kHz	As defined by -3 dB point
R_S	Analog Source Impedance[4]	–	–	10	kΩ	In unbuffered mode
				500	kΩ	In buffered modes
Zin	Input Impedance	–	150		kΩ	In unbuffered mode at 20MHz[5]
		10	–		MΩ	In buffered modes
Vin	Input Voltage Range	0		V_{DD}	V	Unbuffered Mode
		0.3		V_{DD}–1.1	V	Buffered Modes These values define the range over which the ADC performs within spec; exceeding these values does not cause damage or instability; see DC Characteristics for absolute pin voltage limits.

Notes:
1. Analog source impedance affects the ADC offset voltage (because of pin leakage) and input settling time.
2. Devices are factory calibrated at V_{DD} = 3.3V and T_A = +30°C, so the ADC is maximally accurate under these conditions.
3. LSBs are defined assuming 10-bit resolution.
4. This is the maximum recommended resistance seen by the ADC input pin.
5. The input impedance is inversely proportional to the system clock frequency.

General Purpose I/O Port Output Timing

Figure 35 and Table 144 provide timing information for GPIO port pins.

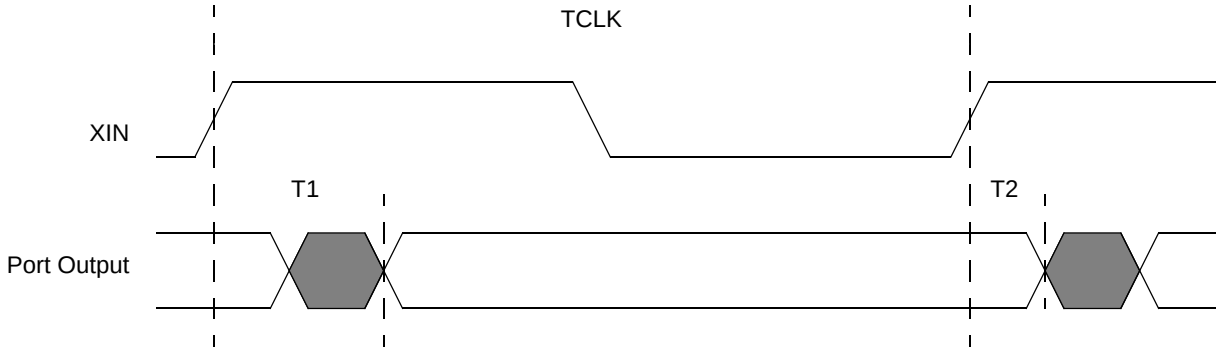

Figure 35. GPIO Port Output Timing

Table 144. GPIO Port Output Timing

		Delay (ns)	
Parameter	**Abbreviation**	**Minimum**	**Maximum**
GPIO port pins			
T_1	X_{IN} Rise to Port Output Valid Delay	–	15
T_2	X_{IN} Rise to Port Output Hold Time	2	–

Table 148. Z8 Encore! XP F082A Series Ordering Matrix

Part Number	Flash	RAM	NVDS	I/O Lines	Interrupts	16-Bit Timers w/PWM	10-Bit A/D Channels	UART with IrDA	Comparator	Temperature Sensor	Description
Z8 Encore! XP F082A Series with 2 KB Flash											
Standard Temperature: 0°C to 70°C											
Z8F021APB020SG	2 KB	512 B	64 B	6	13	2	0	1	1	0	PDIP 8-pin package
Z8F021AQB020SG	2 KB	512 B	64 B	6	13	2	0	1	1	0	QFN 8-pin package
Z8F021ASB020SG	2 KB	512 B	64 B	6	13	2	0	1	1	0	SOIC 8-pin package
Z8F021ASH020SG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SOIC 20-pin package
Z8F021AHH020SG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SSOP 20-pin package
Z8F021APH020SG	2 KB	512 B	64 B	17	19	2	0	1	1	0	PDIP 20-pin package
Z8F021ASJ020SG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SOIC 28-pin package
Z8F021AHJ020SG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SSOP 28-pin package
Z8F021APJ020SG	2 KB	512 B	64 B	25	19	2	0	1	1	0	PDIP 28-pin package
Extended Temperature: –40°C to 105°C											
Z8F021APB020EG	2 KB	512 B	64 B	6	13	2	0	1	1	0	PDIP 8-pin package
Z8F021AQB020EG	2 KB	512 B	64 B	6	13	2	0	1	1	0	QFN 8-pin package
Z8F021ASB020EG	2 KB	512 B	64 B	6	13	2	0	1	1	0	SOIC 8-pin package
Z8F021ASH020EG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SOIC 20-pin package
Z8F021AHH020EG	2 KB	512 B	64 B	17	19	2	0	1	1	0	SSOP 20-pin package
Z8F021APH020EG	2 KB	512 B	64 B	17	19	2	0	1	1	0	PDIP 20-pin package
Z8F021ASJ020EG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SOIC 28-pin package
Z8F021AHJ020EG	2 KB	512 B	64 B	25	19	2	0	1	1	0	SSOP 28-pin package
Z8F021APJ020EG	2 KB	512 B	64 B	25	19	2	0	1	1	0	PDIP 28-pin package

Z